

Title (en)

DEVICE AND METHOD FOR THE ETCHING OF SUBSTRATES

Title (de)

VORRICHTUNG UND VERFAHREN ZUM ÄTZEN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF DE GRAVURE DE SUBSTRATS

Publication

**EP 1853752 A1 20071114 (DE)**

Application

**EP 06707264 A 20060224**

Priority

- EP 2006001728 W 20060224
- DE 102005011298 A 20050304

Abstract (en)

[origin: WO2006094657A1] According to the invention, the etching of, for example, conductor structures on circuit boards (21) with etching fluid may be improved, whereby the etching fluid is sprayed onto the circuit board (21) as an aerosol spray (17), or similar. By means of contacting a corresponding spraying device (13, 14) to one pole and the circuit board (21) to the other pole of a DC supply (23), the etching process can be assisted and in particular, accelerated.

IPC 8 full level

**C25F 7/00** (2006.01); **H05K 3/07** (2006.01)

CPC (source: EP)

**C25F 7/00** (2013.01); **H05K 3/07** (2013.01); **H05K 2203/075** (2013.01); **H05K 2203/105** (2013.01)

Citation (search report)

See references of WO 2006094657A1

Designated contracting state (EPC)

AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HU IE IS IT LI LT LU LV MC NL PL PT RO SE SI SK TR

DOCDB simple family (publication)

**DE 102005011298 A1 20060907**; CN 101163823 A 20080416; CN 101163823 B 20110413; EP 1853752 A1 20071114; WO 2006094657 A1 20060914

DOCDB simple family (application)

**DE 102005011298 A 20050304**; CN 200680006806 A 20060224; EP 06707264 A 20060224; EP 2006001728 W 20060224